

REMARKS

Claims 1-9 are pending in this application.

The May 14, 2008 Office Action does not clearly indicate whether the certified copy of the priority document has been received by the Patent Office from the International Bureau. The December 9, 2008 Office Action also fails to respond to Applicants' request for clarification. Such indication is, again, respectfully requested in the next Office Action.

The Office Action rejects claims 1, 2, 4-6, 8 and 9 under 35 U.S.C. §102(a) over U.S. Patent Publication No. 2003/0138596 to Harada; and rejects claims 3 and 7 under 35 U.S.C. §103(a) over Harada in view of JP 2002-102627 to Norihiko or WO 03/31371 to Fujita.¹ These rejections are respectfully traversed.

Independent claims 1 and 4 recite that the first plurality of protrusion portions are embedded in the adhesive layer. Harada does not disclose this feature.

The Office Action asserts that Harada's heat-conductive members 18 and 19 correspond with the recited protrusion portions. However, as shown in Fig. 3 and discussed in paragraphs [0060] and [0061] of Harada, the heat-conductive members 18 and 19 are not embedded in the bonding material 24. Instead, the heat-conducting members 18 and 19 are clearly separated from the bonding material 24 in Fig. 3 of Harada. Also, paragraph [0068] of Harada discloses that it is preferable that the bonding material be composed of a heat-conductive component, so as to secure thermal conductivity both at the conduct portions 8 and 9 and at the bonding parts 35 and 36. The contact portions 8 and 9 are associated with the heat-conductive members 18 and 19, while the bonding parts 35 and 36 are associated with the bonding material 24. Thus, paragraph [0068] of Harada clearly indicates that the heat-conductive members 18 and 19 are separate components from the bonding material 24.

¹ The Office Action appears to misidentify claims in the rejection. It is believed that claim 2 is rejected under 35 U.S.C. §102(a), while claim 7 is rejected under 35 U.S.C. §103(a).

In view of the above, Harada does not disclose the above-discussed imbedding feature recited in claims 1 and 4. Norihiko and Fujita do not cure the deficiencies of Harada. Thus, claims 1 and 4 are patentable over the applied references. Claims 2, 3 and 5-9 are also patentable over the applied references at least in view of the patentability of claims 1 and 4, from which they depend, as well as for additional features they recite. Accordingly, withdrawal of the rejection of claims 1-9 under 35 U.S.C. §102(a) and §103(a) is respectfully requested.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1-9 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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